

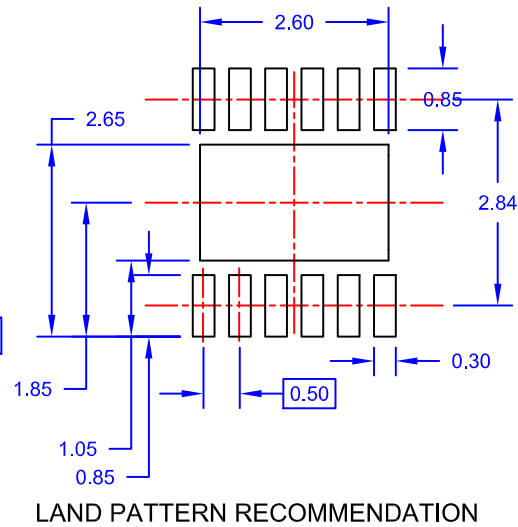
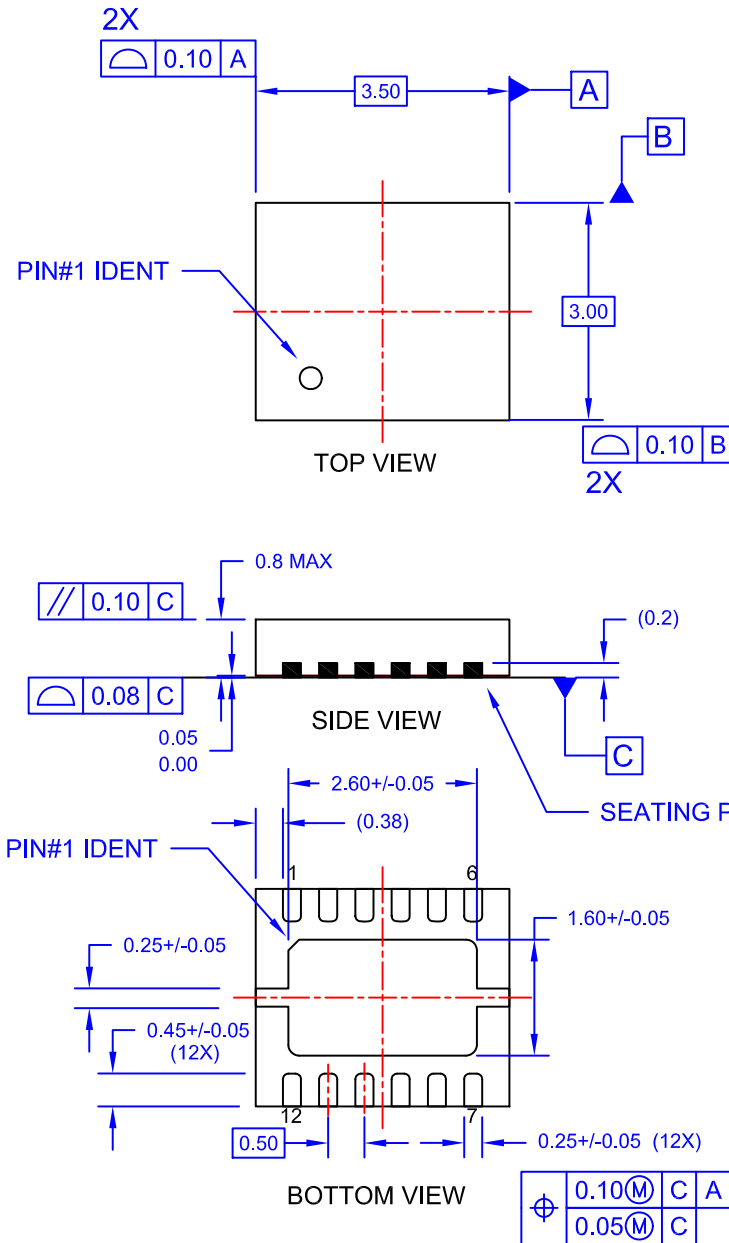
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®



**WDFN12 3.5x3, 0.5P**  
CASE 511DK  
ISSUE O

DATE 31 AUG 2016



**NOTES:**

- A. CONFORMS TO JEDEC MO-229 VARIATION WFED-2.
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. LANDPATTERN RECOMMENDATION IS BASED ON IPC 7351 DESIGN GUIDELINES
- E. LANDPATTERN EXTENSION TO INCLUDE CENTER PAD TABS IS OPTIONAL

<b>DOCUMENT NUMBER:</b>	<b>98AON13627G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>WDFN12 3.5X3, 0.5P</b>	<b>PAGE 1 OF 1</b>

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.